

S/N 10/623,788

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Leonard Forbes et al.	Examiner:	Pamela Perkins
Serial No.:	10/623,788	Group Art Unit:	2822
Filed:	July 21, 2003	Docket No.:	1303.109US1
Customer No.:	73115	Confirmation No.:	6087
Title:	STRAINED SEMICONDUCTOR BY FULL WAFER BONDING		

COMMUNICATION RE: FEE ADDRESS

Mail Stop Issue Fee
Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

In response to the Notice of Allowance and Issue Fee Due, please record the Fee Address under the provisions of 37 CFR 1.363 as the following:

Customer Number 26809

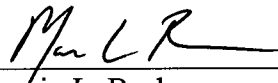
which is associated with Micron Technology, Inc..

Please direct any inquiries to the undersigned attorney at (612) 373-6960.

Respectfully submitted,

SCHWEGMAN, LUNDBERG & WOESSNER, P.A.
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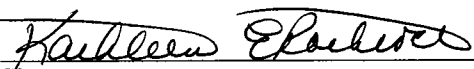
Date 9-17-08

By 
Marvin L. Beekman
Reg. No. 38,377

MLB:CMG:ker1

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is filed using the USPTO's electronic filing system EFS-Web, and is addressed to: Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 17 day of September, 2008.

KATHLEEN E. ROTHROCK
Name


Signature